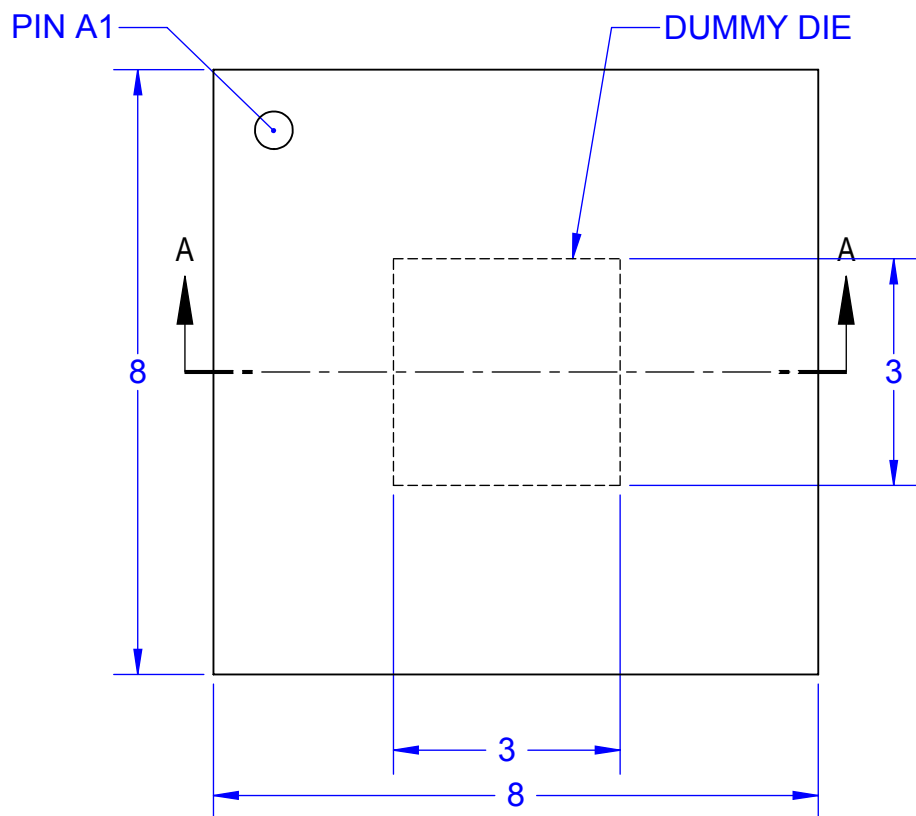
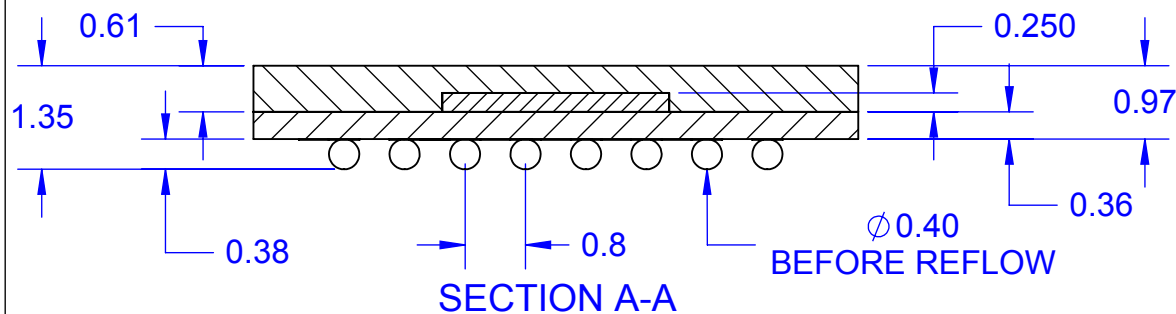
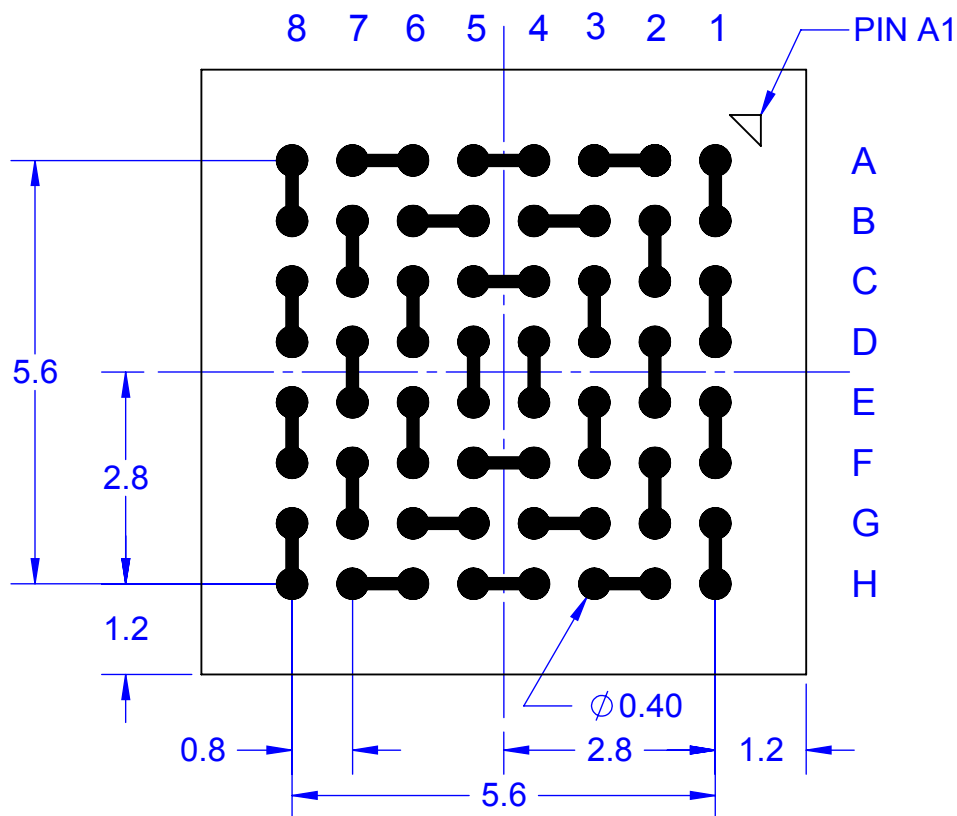


TOP VIEW



BALL VIEW




Notes: (Unless Otherwise Specified).

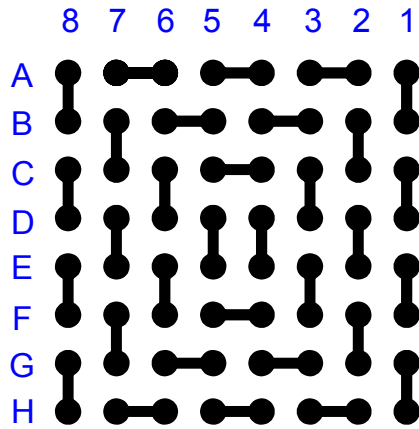
- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- 3) BALL DIAMETER (BEFORE REFLOW): 0.40mm.
- 4) SOLDER MASK DEFINED PAD OPENING: 0.32mm [13 MIL].
- 5) PAD Cu DIAMETER: 0.406mm [16 MIL].
- 6) SUBSTRATE MATERIAL: BT.
- 7) DUMMY DIE: 0.250mm [10 MIL] THICK.
- 8) DAISY CHAIN PATTERN (SEE PAGE 2).
- 9) MSL-3 RECOMMEND BAKING 24 HOURS @ 125C TO REMOVE MOISTURE PRIOR TO SOLDERING TO PC BOARD.

SECTION A-A

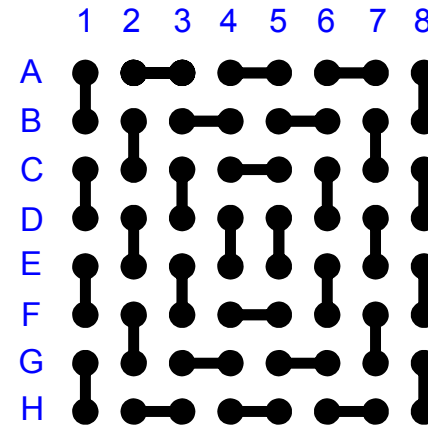
PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	Pb-FREE	RoHS	Si DIE
BGA64T.8C-DC089D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES
LGA64T.8G-DC089D	NONE	YES	YES	YES
BGA64T.8-DC089D	Sn63/Pb37	NO	NO	YES

APPROVALS		DATE			
DRAWN	T. Au	11/11/12			
ENG	M. Hart	11/11/12	TITLE		
MFG			BGA64T.8C-DC089D DAISY CHAIN DUMMY		
QA			SCALE	SIZE	DRAWING NO.
CUST				A	580893
REVISED			DO NOT SCALE DRAWING		SHEET 1 OF 2

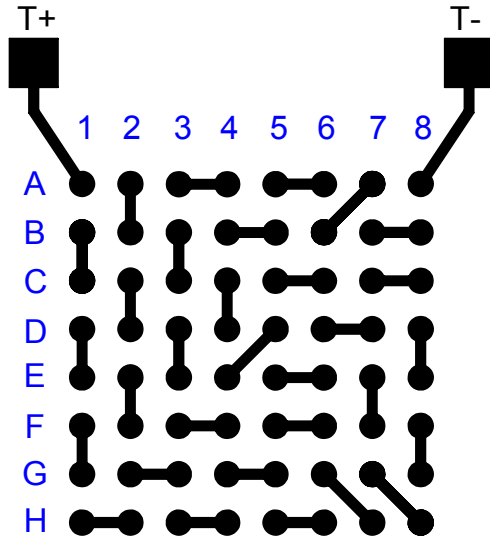
BALL VIEW



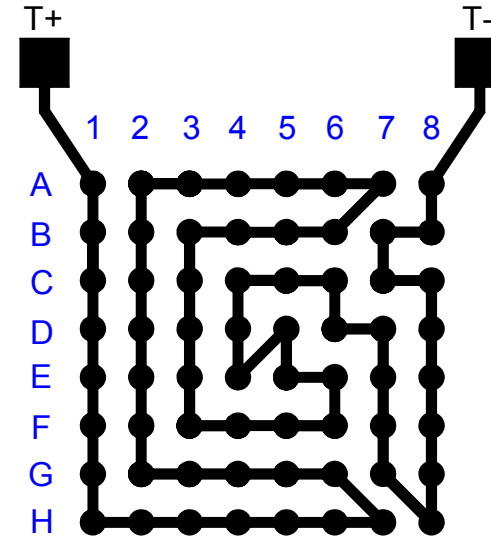
BOTTOM SIDE
(TOP X-RAY VIEW)



TOP VIEW



AFTER MOUNTING
TO TEST BOARD
(TOP X-RAY VIEW)



TEST VEHICLE BOARD

Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.406mm [16 MIL].
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.152mm [6 MIL].
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING 0.320mm [13 MIL].

TopLine®			
TITLE		BGA64T.8C-DC089D DAISY CHAIN DUMMY	
SCALE	SIZE	DRAWING NO.	REV
	A	580893	A
DO NOT SCALE DRAWING			SHEET 2 OF 2